

Features

- High isolation 3750 VRMS
- DC input with random-phase photo triac output
- Operating temperature range - 40 °C to 100 °C
- REACH & RoHS compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
 - UL - UL1577
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC - GB4943.1

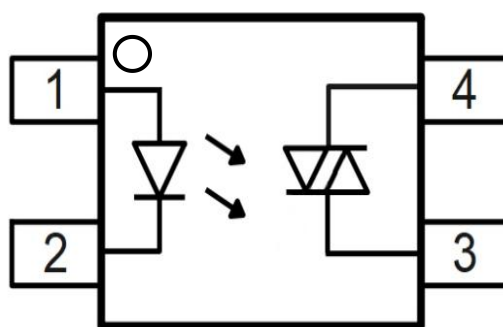
Applications

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

Description

The MOC302X-S and MOC305X-S series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic SOP4 package.

With the robust coplanar double mold structure, MOC302X-S/MOC305X-S series provide the most stable isolation feature.



ORDERING INFORMATION

Outline	Part Number	Package	Marking	Packing	Packing Size	Quantity
	MOC302X-SVSE(1)	SOP4	MOC30XX /YYWW A	Reel	13 "	3000
	MOC305X-SVSE(1)					

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PIN CONFIGURATION AND FUNCTIONS

	Pin	Name
	1	Anode
	2	Cathode
	3	Terminal
	4	Terminal

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit	Note
INPUT				
Forward Current	I_F	60	mA	
Reverse Voltage	V_R	6	V	
Junction Temperature	T_j	125	°C	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Off-state Output Terminal Voltage	MOC302X-S	V_{DRM}	400	V
	MOC305X-S		600	
Peak Repetitive Surge Current PW=100μs, 120pps	I_{TSM}	1	A	
Junction Temperature	T_j	125	°C	
Output Power Dissipation	P_O	300	mW	
COMMON				
Total Power Dissipation	P_{tot}	330	mW	
Isolation Voltage	V_{iso}	3750	Vrms	1
Operating Temperature	T_{opr}	-40~100	°C	
Storage Temperature	T_{stg}	-55~125	°C	
Soldering Temperature	T_{sol}	260	°C	2

Note 1. AC For 1 Minute, R.H. = 40 ~ 60%

Note 2. For 10 seconds

ELECTRICAL OPTICAL CHARACTERISTICS(T_a=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Note
INPUT							
Forward Voltage	V _F	-	1.24	1.4	V	I _F =10mA	
Reverse Current	I _R	-	-	10	μA	V _R =6V	
Input Capacitance	C _{in}	-	8.5	250	pF	V=0, f=1kHz	
OUTPUT							
Peak Off-state Current, Either Direction	I _{DRM}	-	-	100	nA	V _{DRM} =Rated V _{DRM} I _F =0	3
Peak On-state Voltage, Either Direction	V _{TM}	-	1.58	2.5	V	I _{TM} =100mA	
Critical Rate of Rise of Off-state Voltage	d _v /d _t	1000	-	-	V/μs	V _{PEAK} =Rated V _{DRM}	4
TRANSFER CHARACTERISTICS							
LED Trigger Current	MOC3021、3051	I _{FT}	-	-	15	Terminal Voltage = 3V I _{TM} =100mA	
	MOC3022、3052		-	-	10		
	MOC3023、3053		-	-	5		
Holding Current	I _H	-	257	-	μA		
Isolation Resistance	R _{iso}	10 ¹²	10 ¹⁴	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C _{IO}	-	0.4	1	pF	V=0, f=1MHz	

Note3. Test voltage must be applied within dv/dt rating.

Note4. Refer to Fig.15 & Fig.16

CHARACTERISTIC CURVES

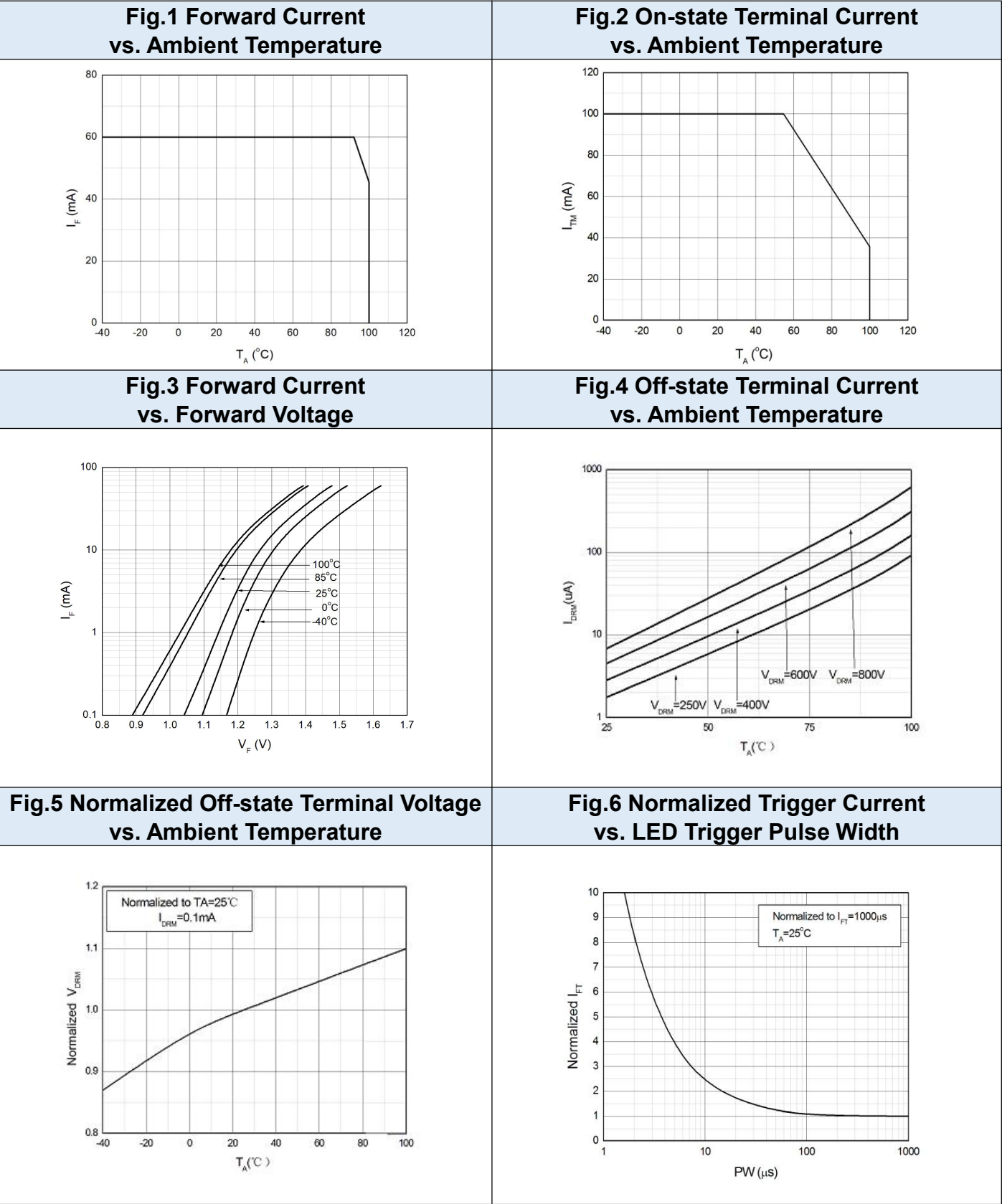


Fig.7 Normalized Trigger Current
vs. Ambient Temperature

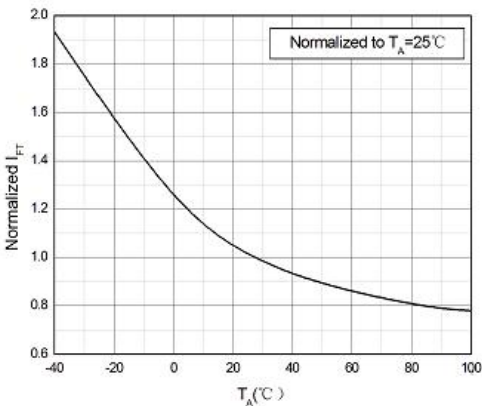


Fig.8 On-state Terminal Voltage
vs. Ambient Temperature

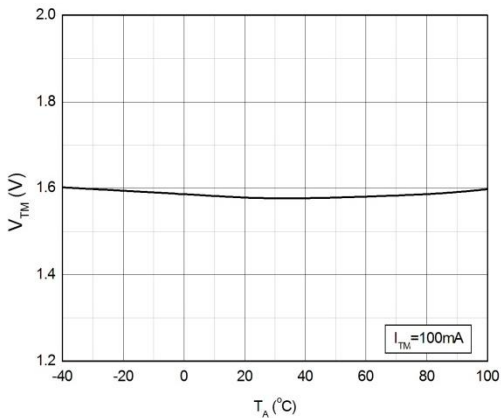


Fig.9 On-state Terminal Voltage
vs. On-state Terminal Current

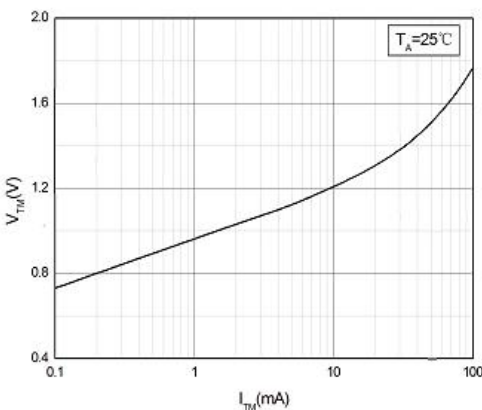


Fig.10 Holding Current
vs. Ambient Temperature

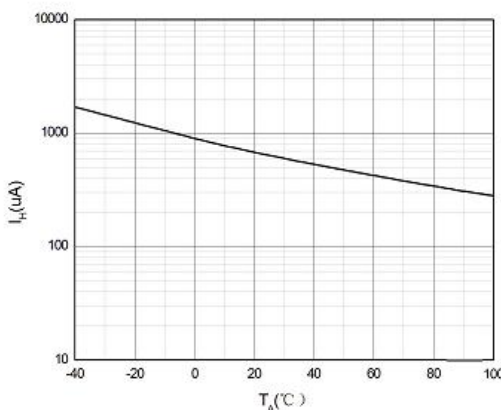


Fig.11 Turn On Time
vs. Forward Current

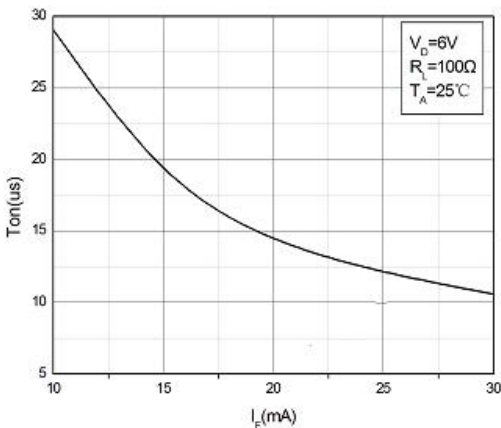
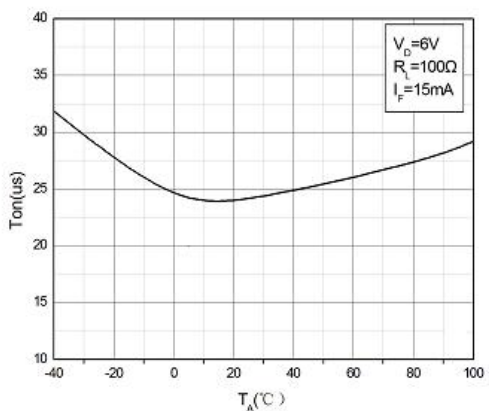


Fig.12 Turn On Time
vs. Ambient Temperature

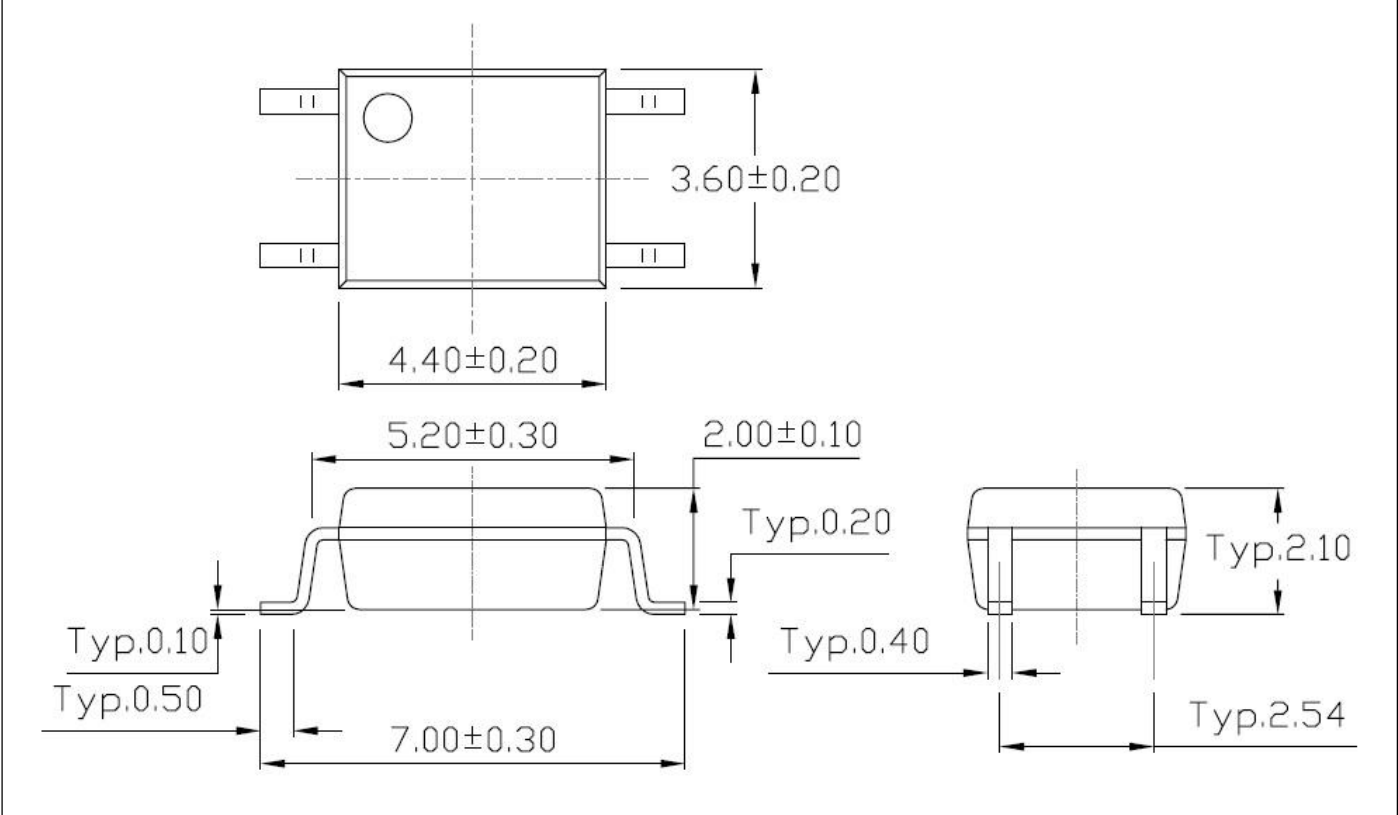


TEST CIRCUITS

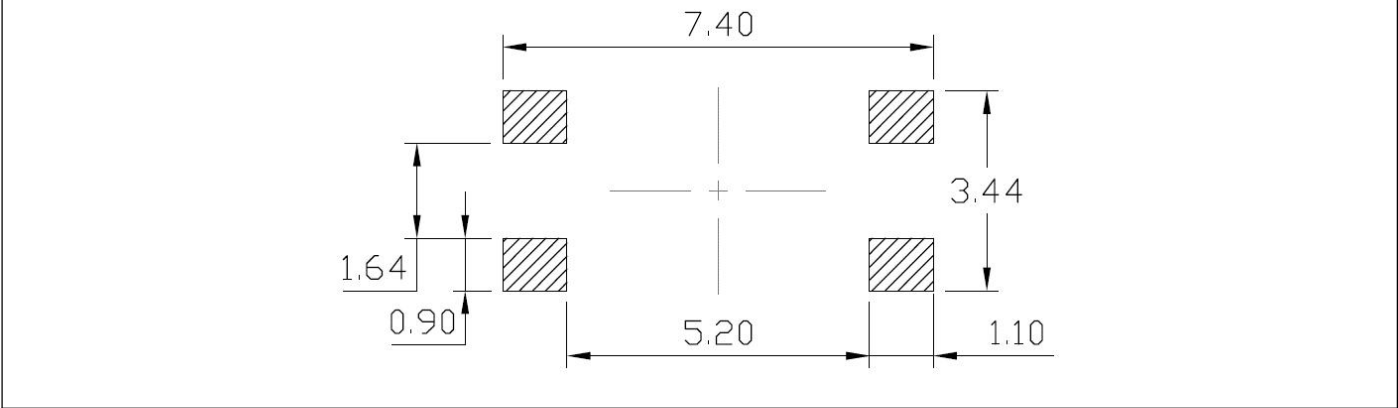
Fig.13 Test Circuits of Turn On Time	Fig.14 Waveforms of Turn On Time
Fig.15 Test Circuits of dV/dt	
Fig.16 Waveforms of dV/dt	
	$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$

PACKAGE DIMENSIONS

Surface Mount (Low Profile) - (SOP4)



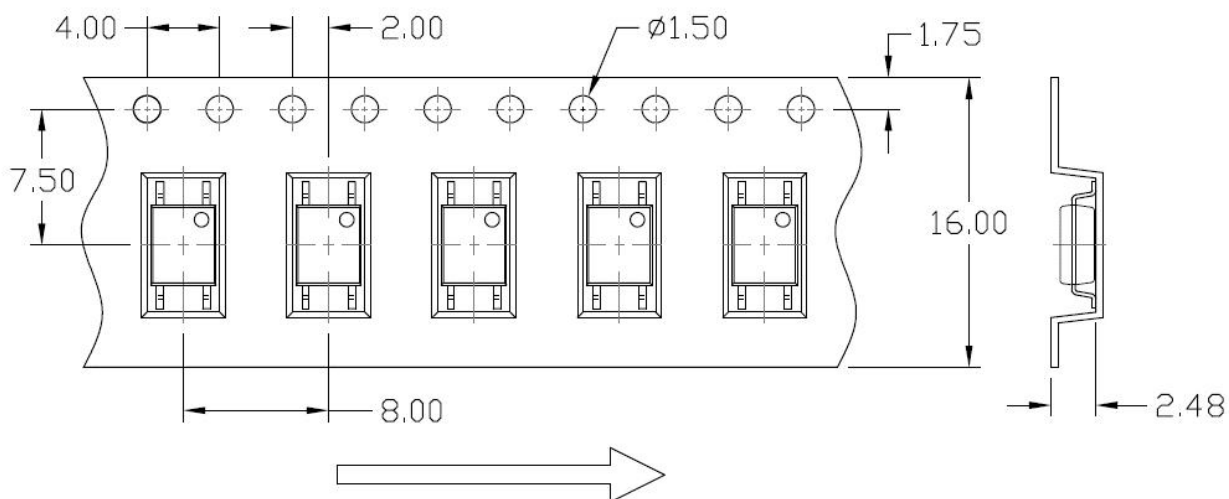
Recommended Solder Mask



- Dimensions in mm unless otherwise stated

CARRIER TAPE SPECIFICATIONS

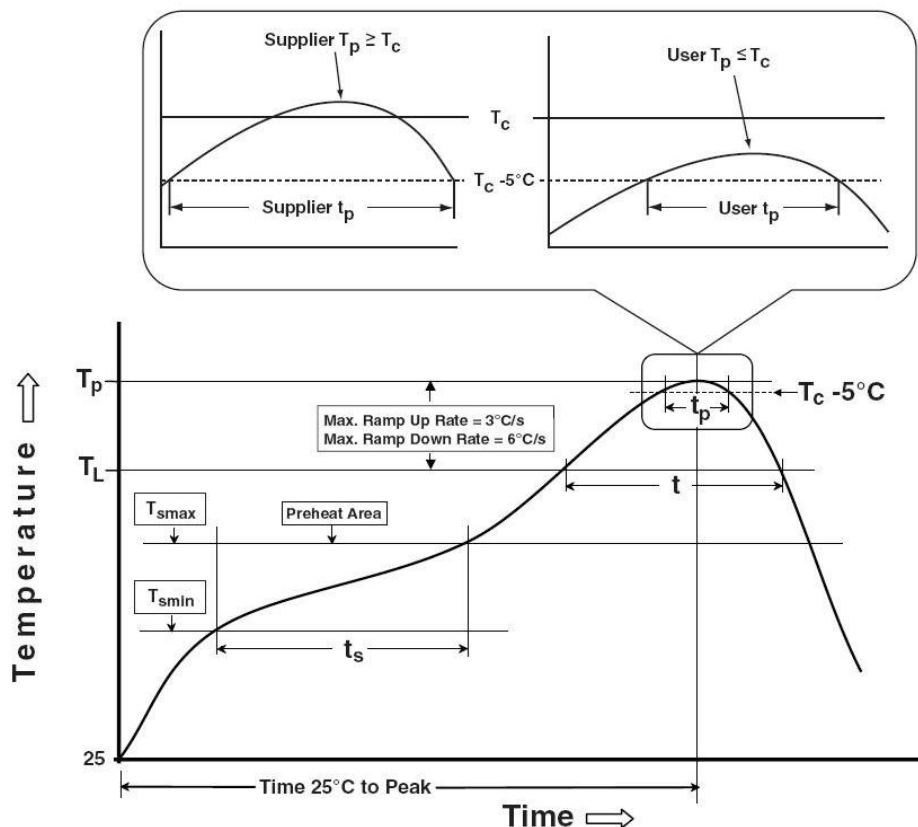
Option SM-SL



- Dimensions in mm unless otherwise stated

REFLOW INFORMATION

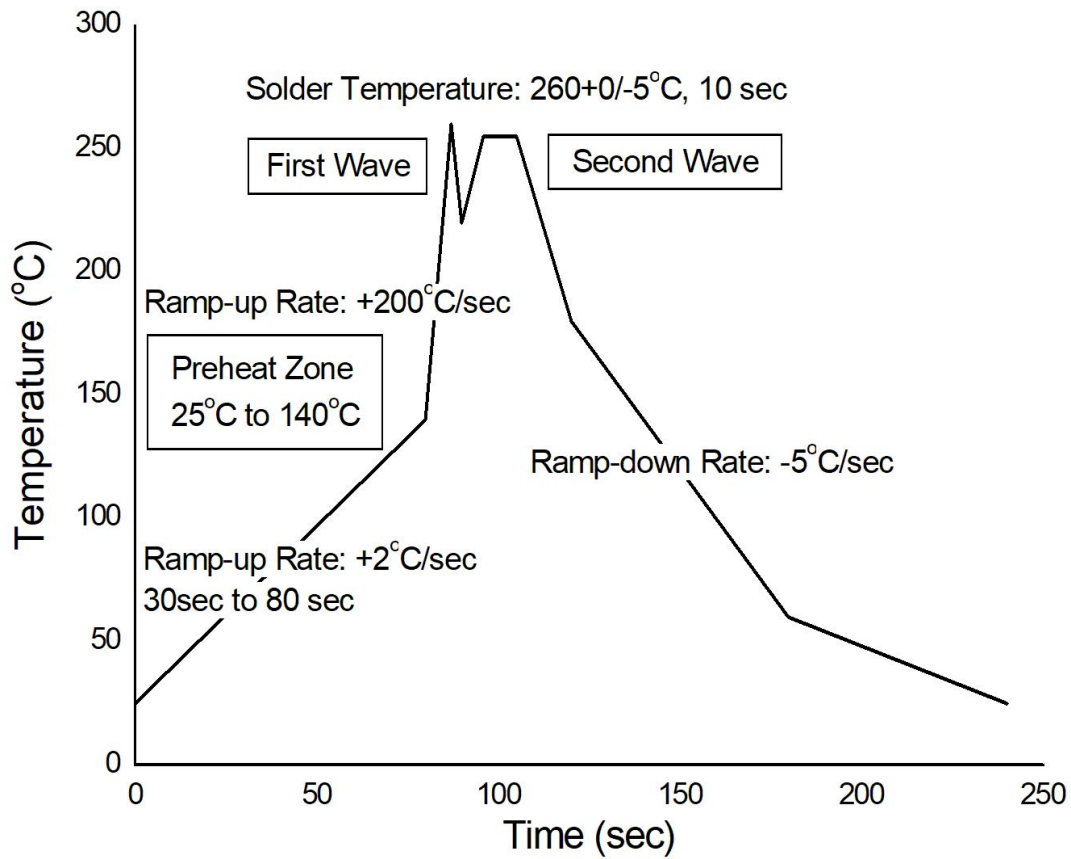
Reflow Profile



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

TEMPERATURE PROFILE OF SOLDERING

Wave Soldering (JESD22-A111 Compliant)



Hand Soldering By Soldering Iron

Soldering Temperature	$380 \pm 0/-5^{\circ}\text{C}$
Soldering Time	3 sec max.

- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.

DISCLAIMER

- ISOMICRON is continually improving the quality, reliability, function and design. ISOMICRON reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
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- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact ISOMICRON sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify ISOMICRON's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.